2006 Financial Year Roadshow

December 6th, 2006

Lehman Brothers Global Technology Conference San Francisco

Dr. Wolfgang ZiebartPresident and CEO





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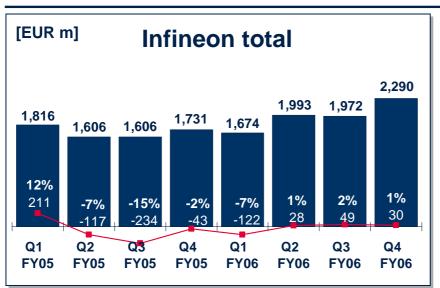
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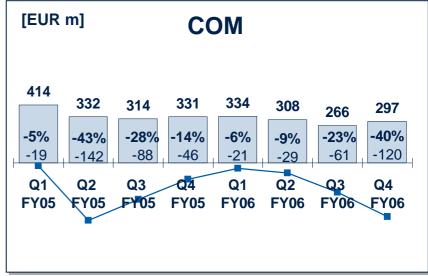


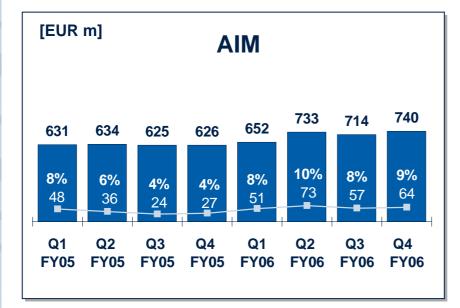


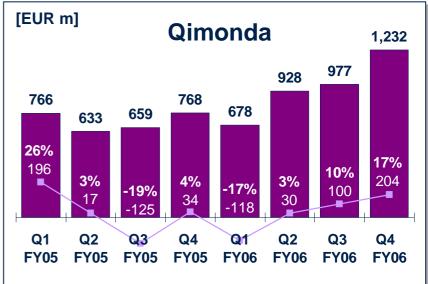


Q4 FY 06 Results: Revenues of EUR 2.29 bn and EBIT of EUR 30 m











Q1 F07 Outlook as per 16-Nov-06

IFX Logic

Q1 F07 sales and EBIT excluding Qimonda and before charges to decrease. Main driver: impact of insolvency of BenQ Mobile's German subsidiary.

COM

- Sales decline of around EUR 50 m q-o-q, loss of BenQ revenue.
- EBIT to decline given lower sales.

AIM

- Revenues flat or down slightly q-o-q
- EBIT to decrease q-o-q. Reasons: seasonality, temporary weakness in US automotive demand, annual auto price breaks, Kulim ramp.

C&E

- EBIT before charges to improve q-o-q.
- Charges of c. EUR 30 m expected relating to baseband re-org.



F2007 Outlook for Select Financial Parameters as per 16-Nov-06

COM

- EUR 40 m annualized cost savings to take effect likely from Jun Q 2007 onwards.
- Target: wireless break-even in Dec quarter 2007.

AIM

- Expect cost for Perlach fab closure to disappear Sep Q 2007.
- Kulim fab to break-even mid-2007 calendar year.
- Chipcard to remain around break-even until new products introduced middle of 2007 calendar year.

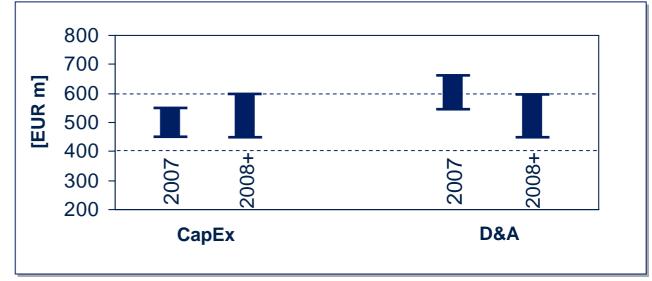
C & E

- Before charges, expect continued moderate q-o-q decline in C&E loss beyond Dec. quarter 2006.
- Total F2007 C&E expense before restructuring to be less than EUR -100 m.

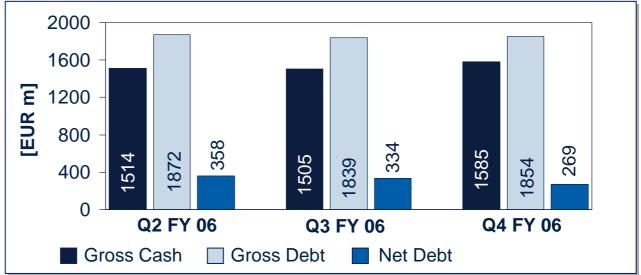


Logic CapEx to equal D&A; solid Financing

Outlook for CapEx and D&A



Financial structure Logic-business for the past quarters





Financials and Outlook
Infineon: Competencies & Drivers
Communication Solutions
Automotive, Industrial & Multimarket
Appendix (Key Financials, Ratios, Financial Calendar)



Key Growth Drivers / Focus Areas

Energy Efficiency (fuel / electricity)

- Improve fuel efficiency in cars
- Efficient power generation, transport, consumption
- Higher efficiency in electrical drives



Mobility & Connectivity

- Mobile phones
- Broadband access
- Wireless connectivity



Security & Safety

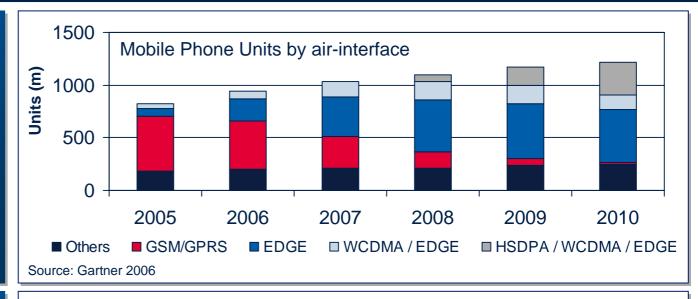
- Protection and privacy of personal and company data
- Secure e-commerce and identification
- Automotive safety



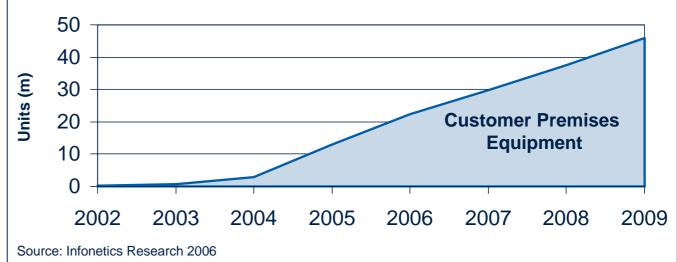


COM Growth Drivers





Connectivity





AIM Growth Drivers

Energy Efficiency

Different governmental requirements:

Europe: Euro 5 norm coming 2009

USA: Energy Star, July 2007, will require PC's to be 65% more power efficient than current models.

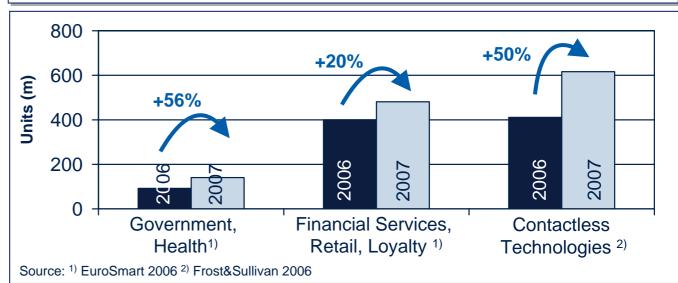
Japan: already highest regulatory standards







Security & Safety





Infineon Competencies

Growth driver

Energy Efficiency, Mobility & Connectivity, Security & Safety

IFX target markets

Automotive

Industrial Electronics

Chipcard & Security

Mobile Phone Platforms

Solutions

BroadbandAccess

IFX Key competencies

Analog / Mixed Signal

RF

Power

Embedded Control



Infineon Businesses

Communication Solutions

Automotive, Industrial & Multimarket

Mobile Phone Platforms

Feature Phones

Entry Phones

Mobile Software



Automotive

Microcontroller

Automotive Power

Sense & Control



RF Solutions

RF Engine

Tuner Systems

Connectivity



Industrial & Multimarket

Power Management & Drive

Discrete Semiconductors



Security & ASICs

ASIC, Design & Security

Chip Card & Security ICs



Access







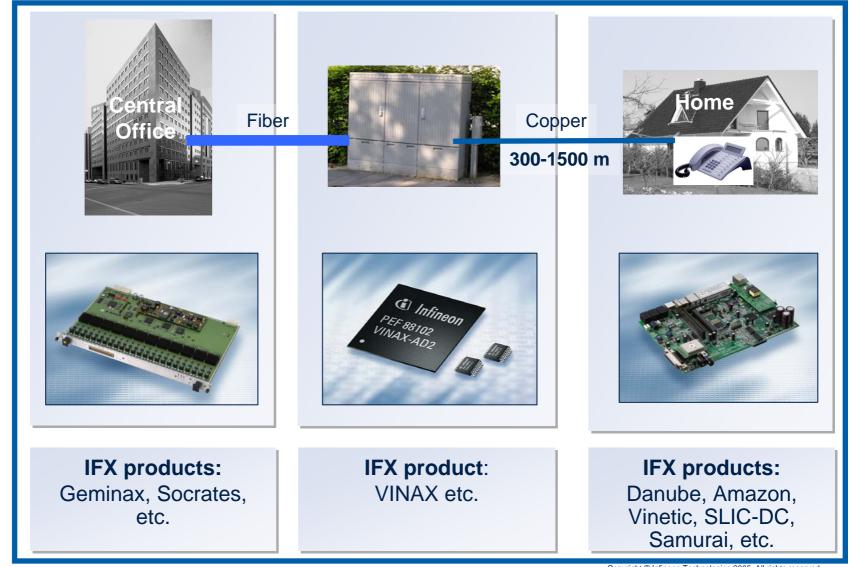
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Automotive, Industrial & Multimarket



Infineon Drives the Entire Broadband Access Chain



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Broadband Access Design-Win Momentum Continues

VDSL2 "VINAX"

Design-Win at major Korean customers

■ Top European customer



ADSL2+ "Geminax-MAX"

Design-Win at two customers based in APAC

Major European customer



ADSL & VoIP "Amazon, Danube"

4 Design-Wins for ADSL & VolP

 2 of the top 5 world wide ADSL-CPE Manufacturer



VoIP "Vinetic"

Design-Wins at two Japanese customers

Major global customer



SHDSL.bis "Socrates-4e"

Leading Chinese DSLAM customer

Major global customer, based in EU





RF Transceiver: CMOS Leadership Turns Into Design-Wins

2 / 2.5 G GSM / GPRS

2.75 G EDGE 3 G WCDMA

SMARTI SD2

SMARTI PM SMARTI PM2 SMARTI 3G SMARTI 3GE

Technology: 130nm CMOS

130nm CMOS

130nm CMOS

Customer	Air Interface	
Samsung	EDGE	
Customer	EDGE	
Customer	WCDMA	
Customer	WCDMA / EDGE	
LG (on platform)	EDGE	
Panasonic (on platform)	WCDMA / EDGE	













World's first WCDMA CMOS RF-Transceiver ✓ in volume



RF/Baseband Integration, HSDPA and More

		2.5G GPRS		75G DGE	3G UMTS	3.5G HSDPA
Platform	ULC1	ULC2		MP-E	MP-EU	MP-EH
Baseband	Dradio	oice	dio	S-GOLD2	S-GOLD2 + co-processor	S-GOLD3H
RF Transceiver	E-GOLDradio	E-GOLDvoice (incl. SRAM)	OLDradio	SMARTI PM	SMARTI PM/3G	SMARTI 3GE
Power Management	E-Powerlite	E-G	S-G	SM-Power	SM-Power1.6	SM-Power3
Protocol Stack	✓	✓	***************************************	✓	✓	✓
Ramp up	✓	1H CY07		✓	✓	CY 2007+

integrated in one chip



Successful Ramp of Shipments to New Wireless Customers



Panasonic





- LG KE820
- Based on IFX EDGE platform (MP-E)
- First model KG99 has been shipped to shops in China in early Oct. 2006
- More models to be launched



- Softbank 705P
- Based on IFX EDGE/3G platform (MP-EU)
- Available in Japan since early October 2006



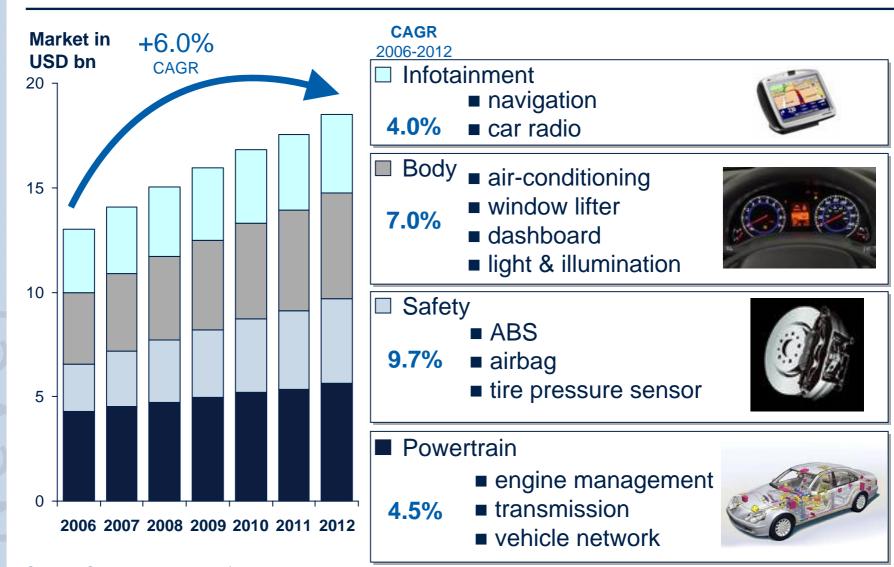
- Samsung D900
- Based on IFX EDGE RF CMOS transceiver (SMARTi PM)
- Launched during Q4 FY06



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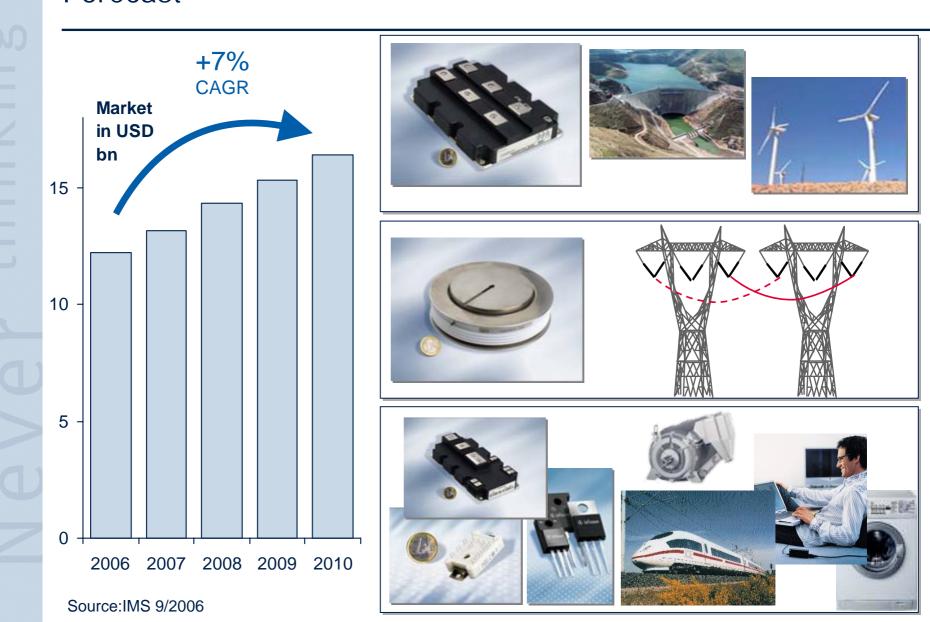


Worldwide Automotive Semiconductor Market Continues to Grow; Safety is the Fastest Growing Segment



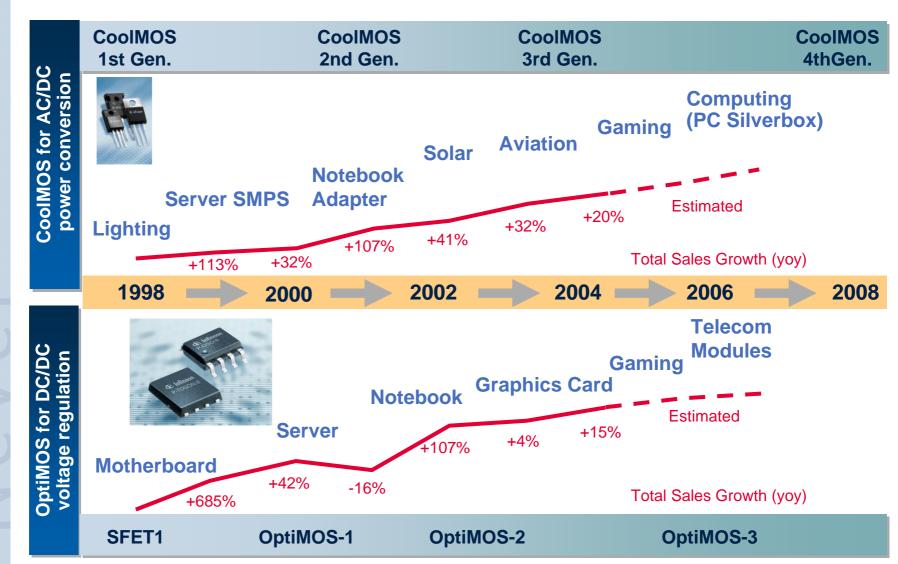


Worldwide Power Semiconductor Market Growth Forecast



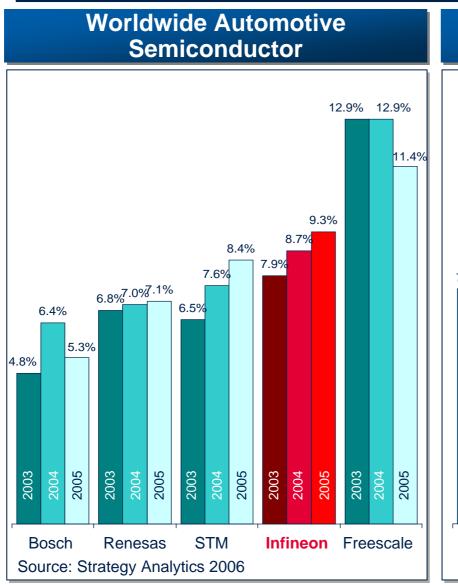


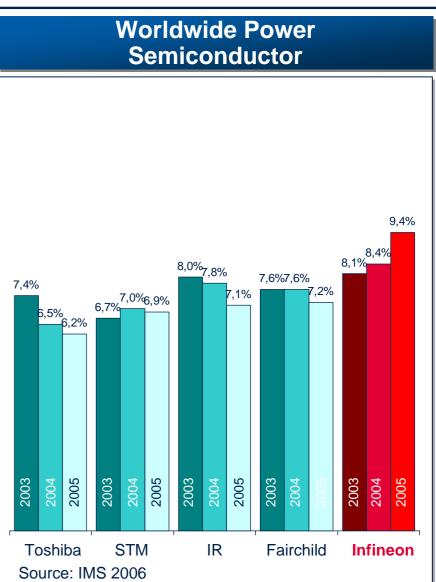
Growth Driver for CoolMOS / OptiMOS: More and More Applications Require Power Efficiency





Infineon's Track Record in Automotive and Power Semiconductor Market Shares











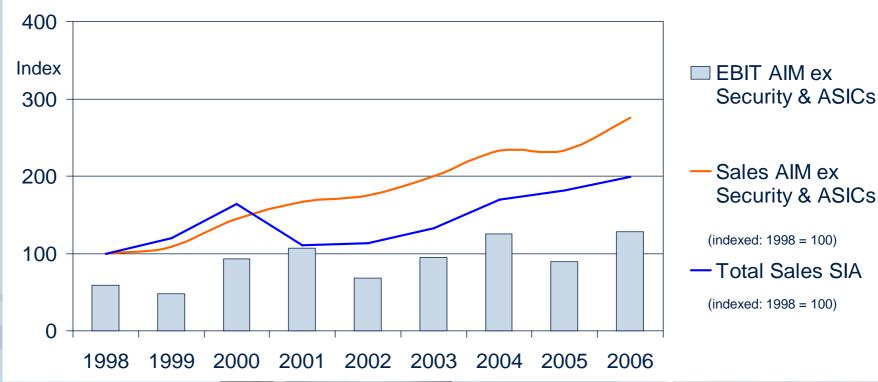


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Profitable Growth: Infineon's AIM ex Security & ASICs*









Key Financials

	Q3 F05	Q4 F05	Q1 F06	Q2 F06	Q3 F06	Q4 F06
Sales (EUR m)	947	964			995	1,058
EBIT (EUR m) EBIT margin	-98 -10.3%	-81 <i>-8.4%</i>			-51 -5.1%	-174 <i>-16.4%</i>
EBIT ex charges (EUR m) EBIT margin ex charges	-27 -2.9%	-8 -0.8%			-22 -2.2%	-11 <i>-1.0%</i>
D&A (EUR m) D&A / Sales (%)	168 <i>17.7%</i>				174 <i>17.5%</i>	172 16.3%
CapEx (EUR m) CapEx / Sales (%)	NM <i>NA</i>				158 <i>15.9%</i>	173 16.4%
PP&E (EUR m)		1,535		1,663	1,660	1,684
Working Capital (EUR m)		463		323	241	454
Gross Cash (EUR m)		1,462		1,514	1,505	1,585
Gross Debt (EUR m)		1,557		1,872	1,839	1,854
Net debt (EUR m)		95		358	334	269
Employees		26,834			29,446	29,849



Financial Calendar

■ Jan 29, 2007*	Interim Report FQ1 2007	Munich
■ Feb 13, 2007	Presentation at 3GSM	Barcelona
■ Feb 15, 2007	Annual General Meeting	Munich
Mar 12/13, 2007*	IFX Day	Campeon Munich
■ Apr 27, 2007*	Interim Report FQ2 2007	Munich
■ Jul 27, 2007*	Interim Report FQ3 2007	Munich
■ Nov 14, 2007*	Interim Report FQ4 2007	Munich

^{* =} Preliminary Date